

ABSTRACT OF THE DISCLOSURE

In image processing method and device used in, for instance, wire bonding, the amount of positional deviation, which is of between a reference image and a rotated image which is obtained by rotating the reference image by a particular angle, is calculated by pattern matching between such two images, and then a first alignment point is determined based upon the calculated amount of the positional deviation and the rotational angle which is a known quantity. By way of using the first alignment point as a reference, pattern matching is executed between the reference image and an image of a comparative object (a semiconductor device, for instance) that is obtained by imaging the comparative object disposed in an attitude that includes positional deviations in the rotational direction, thus minimizing the error in the detected position of the comparative object.